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NOV 24 2006

Amendments to the specification:

Please make the following amendments to the specification. Material to be inserted in replacement paragraphs or sections is in **bold and underline**, and material to be deleted is in ~~strikeout~~ or (if the deletion is of five or fewer consecutive characters or would be difficult to see) in double brackets [[]].

Please replace the paragraph beginning at page 15, line 7 with the following amended paragraph:

A specific example of a material that forms redeposited cones is one of the materials, KAPTON® E, used to make the flexible circuits used in print cartridge assemblies, 10 in Fig. 1. This polyimide material forms redeposited cones at fluences of 55-75 mJ/cm²/pulse using 248 nm ~~eximer~~excimer at a few up to 500 shots and frequencies from 1 to at least 200 Hz. 60 mJ/cm²/pulse, 70 shots at 200 Hz being optimal. As is known in the art, the measurement of fluence varies with the measurement techniques and beam delivery system. Therefore, the exact processing conditions for a given material needs to be determined experimentally on the system being used for the process.

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Serial No. 10/052,815
HP Docket No. 10012053-1
KH Docket No. HPCC 321

Please replace the paragraph beginning at page 6, line 14 with the following amended paragraph:

Adhesive, as used herein, is generally defined as any substance that may be coupled to the treated surface of the substrate. Adhesive includes any material that provides or promotes adhesion between the substrate and the material itself. Any material that may flow or conform and adhere to the surface of the substrate and that provides or promotes such adhesion may be an adhesive. For example, conventional polymeric adhesives may be used, liquid adhesives, hot melt adhesives, liquid coatings including thermoplastic film adhesives, thermosetting film adhesives, epoxy films. In addition, the term adhesive refers to, electro-deposited metal, cast metal, vapor deposited materials (organic, inorganic or metallic), organic and inorganic coatings. The adhesive also may itself be a second component that is to be attached to the substrate for example a part may be treated and a second more compliant part may be pressed into the treated part creating a bond.

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